



General-Purpose Low-Temperature Silver Paste, Curing At 80–200°C

P/N	Ingredient	Main Features & Applications
Main Features	Low-Temperature Silver Paste	<p>① It can be produced through screen printing, dispensing, or spray application after dilution (requires the use of a dedicated diluent ST1001).</p> <p>② It can be applied to hard substrates such as ceramics, glass, and PCB, as well as soft substrates like PET, PC, and PI, providing excellent conductivity and film adhesion.</p> <p>③ It exhibits excellent printability, antioxidant resistance, flexibility, and strong adhesion, allowing bending without significant change in electrical resistance.</p> <p>④ Thin-film switches, flexible printed circuits, keyboard circuits, shielded wiring, multilayer circuit printing, RF interference shielding, RFID, toy circuits, learning machine circuits, and other fields such as printing and contact printing</p> <p>⑤ After curing, the temperature resistance is below 200°C, and briefly below 300°C.</p>
01L-2211D	Low-Temperature Silver Paste	Bake at 80–120°C (up to 200°C)
01L-2210	Low-Temperature Silver Paste	The upgraded version of 01L-2211D features lower resistivity ($\leq 20\text{m}\Omega/\square$), recommended by the store manager.

Product Specification

Product:	Low-Temperature Silver Paste
Part Number:	01L-2211D

- ※ Silver paste cured at 80–200°C
- ※ Compatible with flexible substrates, ceramics, glass, and metals
- ※ Suitable for dispensing and printing
- ※ High silver content with low electrical resistance
- ※ Exceptional adhesion and oxidation resistance



※ Bendable without significant resistance change

- ※ 80 ~ 200°C sưởi ấm bảo dưỡng bạc dán
- ※ Thích hợp cho chất nền linh hoạt, gồm sứ, thủy tinh, kim loại và các chất nền khác
- ※ Pha chế và in ấn có sẵn
- ※ Hàm lượng bạc cao và điện trở thấp
- ※ Độ bám dính mạnh và khả năng chống oxy hóa tốt
- ※ Nó có thể được uốn cong, và điện trở sẽ không thay đổi đáng kể sau khi uốn cong

Application Scope :

The single-component conductor paste series is widely applicable in various fields including thin-film switches, flexible printed circuits, laptop keyboard circuits, mobile phone keyboard shielding lines, multilayer circuit printing, RF interference shielding, RFID, toy manufacturing, educational device circuit printing, and contact printing. It can be used on substrates such as alumina ceramics, microcrystalline glass ceramics, PET, and PC, providing excellent conductivity and film adhesion. The product features superior printability, oxidation resistance, flexibility, and strong adhesion. Its conductivity remains stable even after processing or bending during product use. It is compatible with both screen printing and spray coating processes.

Usage Conditions :

Substrate	Ceramic substrates, PET, PI polyester films, and other sheet materials	
Usage Method	200-250 mesh screen printing	
Leveling	Level at room temperature for 3-5 minutes (time adjusted according to actual leveling conditions)	
Solidify	In an incubator, or continuous hot air (choose one of the following conditions)	
	80°C	60 minutes
	120°C	20 minutes
	150°C	10 minutes
	180°C	5 minutes
Thinner	ST-1001	

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	$\leq 8\mu\text{m}$	FOG test



2	Viscosity	80-220Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, 10 rpm, with adjustable viscosity at 25±1°C according to user requirements.
3	Solid Content	65-80%	Silver, Glue

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1)

Characteristics	Standard	Test Method And Conditions	
4 Resistivity	≤20mΩ/□	Square resistance test The cured film thickness is 10μm, and the test pattern size is 100mm*1mm.	
	≤10mΩ/□	Four-pin probe method 25.4u	
5 Hardness	3H	Pencil hardness	
6 Adhesion	Not fall off	3M 600#Tape 90°Pull	

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of six months from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.